



## Description

### Features

- Extremely Low RDS(on): 3.8 mΩ @ V<sub>GS</sub>=10 V, I<sub>D</sub>=40 A
  - Good stability and uniformity
  - 100% avalanche tested
- Excellent package for good heat dissipation

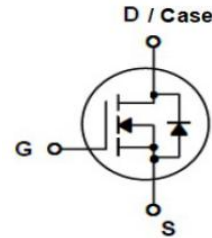
### General Description

The 3080 uses advanced trench Typ. RDS(on) = 3.8 mΩ technology to provide excellent RDS(ON), low gate charge This device is suitable for use in UPS, power switching and general purpose applications.

### Package



TO-252



## Thermal Characteristics

Symbol	Parameter	Value	Units
R <sub>θJC</sub>	Thermal Resistance, Junction-to-Case	1.85	°C/W

## Absolute Maximum Ratings (T<sub>C</sub>=25°C unless otherwise specified)

Symbol	Parameter	Value	Units
V <sub>DS</sub>	Drain-Source Voltage	30	V
I <sub>D</sub>	Drain Current - Continuous (TC= 25°C)	80	A
	- Continuous (TC= 100°C)	51*	A
I <sub>DM</sub>	Drain Current - Pulsed (Note 1)	190*	A
V <sub>GS</sub>	Gate-Source Voltage	± 20	V
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 2)	200	mJ
P <sub>D</sub>	Power Dissipation (TC = 25°C)	82	W
	- Derate above 25°C	0.54	W/°C
T <sub>j</sub> , T <sub>stg</sub>	Operating and Storage Temperature Range	-55 to +175	°C

\* Drain current limited by maximum junction temperature



#### Electrical Characteristics (TC = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units	
<b>Off Characteristics</b>							
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 250\ \mu\text{A}$	30			V	
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 30\text{ V}, V_{GS} = 0\text{ V}$			1	$\mu\text{A}$	
$I_{GSSF}$	Gate Leakage Current, Forward	$V_{GS} = 20\text{ V}, V_{DS} = 0\text{ V}$			100	nA	
$I_{GSSR}$	Gate Leakage Current, Reverse	$V_{GS} = -20\text{ V}, V_{DS} = 0\text{ V}$			-100	nA	
<b>On Characteristics</b>							
$V_{GS(TH)}$	Gate Threshold voltage	$V_{DS} = V_{GS}, I_D = 250\ \mu\text{A}$	1	1.5	2	V	
$R_{DS(on)}$	Drain-Source on-state resistance	$V_{GS} = 10\text{ V}, I_D = 40\text{ A}$		3.8	4.8	m $\Omega$	
		$V_{GS} = 4.5\text{ V}, I_D = 24\text{ A}$		5.1	7.3	m $\Omega$	
gFS	Forward Transconductance	$V_{DS} = 5\text{ V}, I_D = 24\text{ A (Note 3)}$	20			S	
<b>Dynamic Characteristics</b>							
$C_{iss}$	Input capacitance	$V_{DS}=25\text{V}, V_{GS}=0\text{V},$ $F=1.0\text{Mhz}$		1800		pF	
$C_{oss}$	Output capacitance			240		pF	
$C_{rss}$	Reverse transfer capacitance			210		pF	
<b>Switching Characteristics</b>							
$t_{d(on)}$	Turn On Delay Time	$V_{DD}=15\text{V}, I_D=60\text{A},$ $V_{GS}=4.5\text{V}, R_G=1.80\Omega$ (Note 3, 4)		11		ns	
$t_r$	Rising Time			160		ns	
$t_{d(off)}$	Turn Off Delay Time			12		ns	
$t_f$	Fall Time			80		ns	
$Q_g$	Total Gate Charge		$V_{DD}=15\text{V}, I_D=30\text{A},$		39		nC
$Q_{gs}$	Gate-Source Charge		$V_{GS}=10\text{V}$ (Note 3, 4)		5		nC
$Q_{gd}$	Gate-Drain Charge			9		nC	
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>							
$I_S$	Maximum Continuous Drain-Source Diode Forward Current				80	A	
$I_{SM}$	Maximum Pulsed Drain-Source Diode Forward Current				190	A	
$V_{SD}$	Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_S = 24\text{ A}$			1.2	V	
$T_{rr}$	Reverse recovery time	$I_F=60\text{A}, di/dt=100\text{A}/\mu\text{S}$		12		ns	
$Q_{rr}$	Reverse recovery charge			2.5		nC	

#### Notes:

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2.  $L = 0.5\text{ mH}, I_{AS} = 35\text{ A}, V_{DD} = 20\text{ V}, R_G = 25\ \Omega$ , Starting  $T_j = 25^\circ\text{C}$
3.  $I_{SD} \leq 40\text{ A}, di/dt = 100\text{ A}/\mu\text{s}, V_{DD} \leq BV_{DSS}$ , Starting  $T_j = 25^\circ\text{C}$
4. Pulse Test : Pulse width  $\leq 300\ \mu\text{s}$ , Duty cycle  $\leq 2\%$
5. Essentially independent of operating temperature



## Typical Performance Characteristics

Figure 1: Output Characteristics

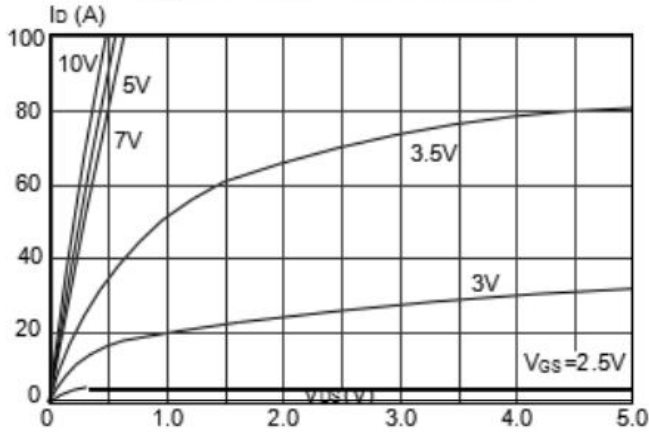


Figure 2: Typical Transfer Characteristics

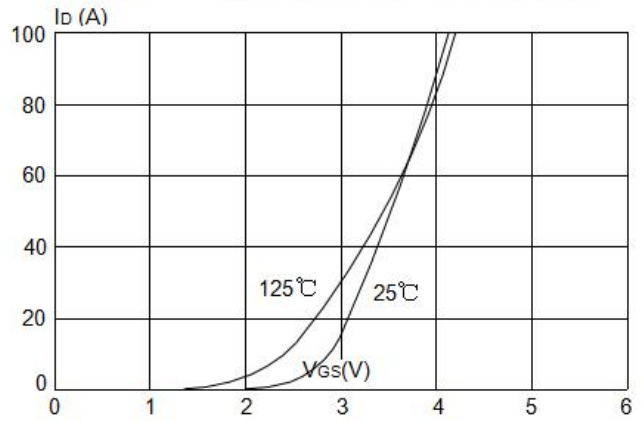


Figure 3: On-resistance vs. Drain Current

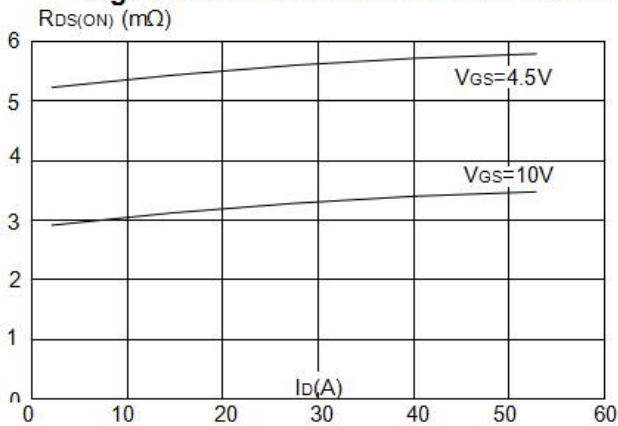


Figure 4: Body Diode Characteristics

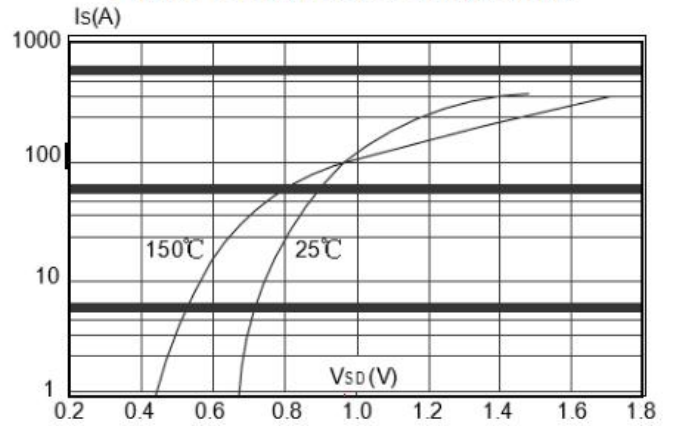


Figure 5: Gate Charge Characteristics

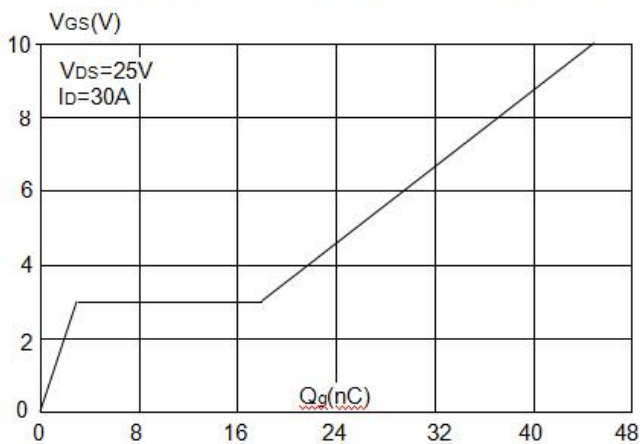
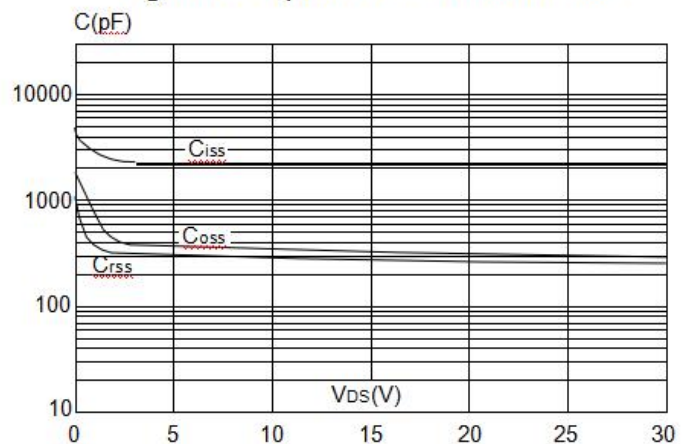
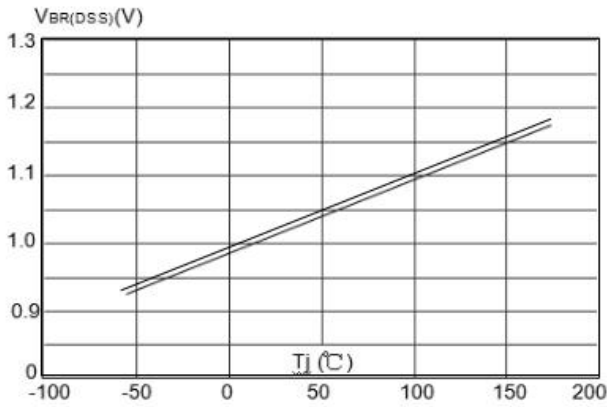


Figure 6: Capacitance Characteristics

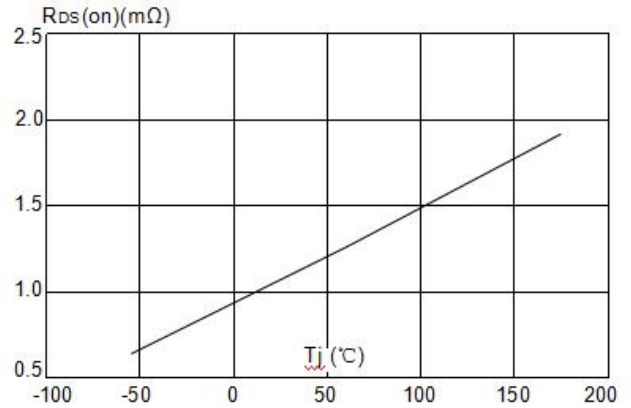




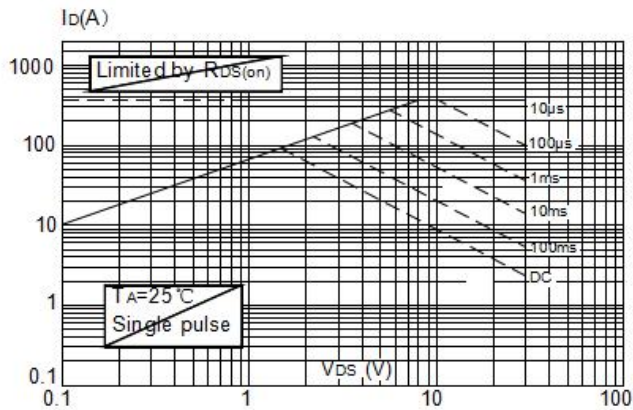
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



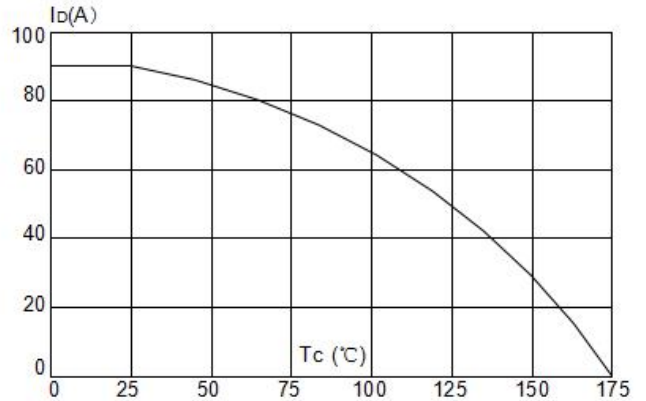
**Figure 8:** Normalized on Resistance vs. Junction Temperature



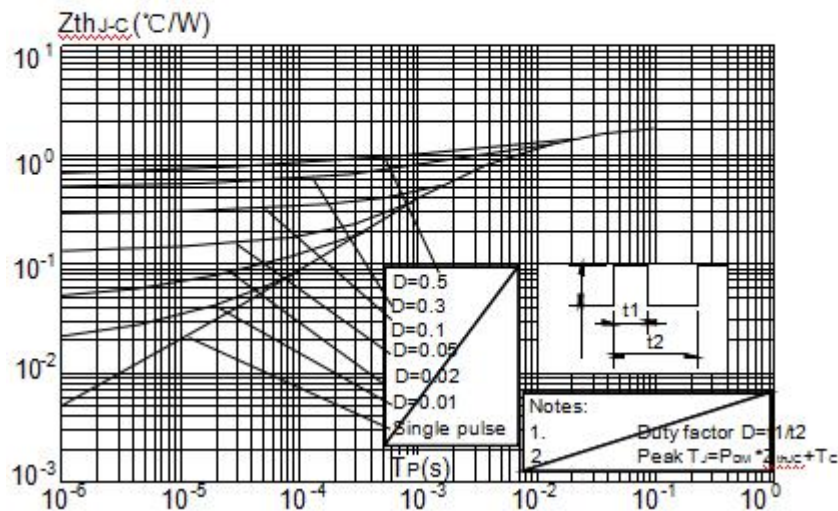
**Figure 9:** Maximum Safe Operating Area



**Figure 10:** Maximum Continuous Drain Current vs. Case Temperature

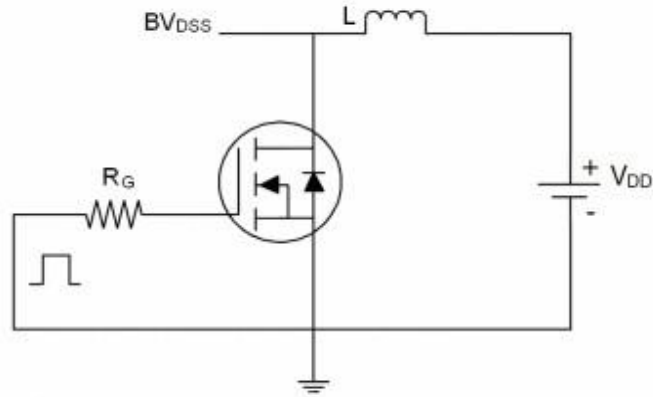


**Figure.11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case (TO-252)

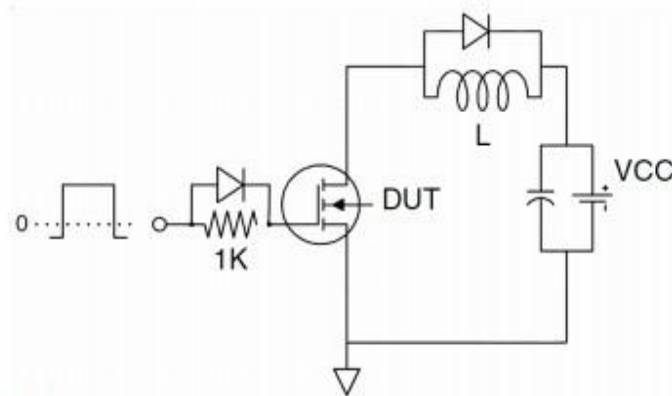


## Test Circuit

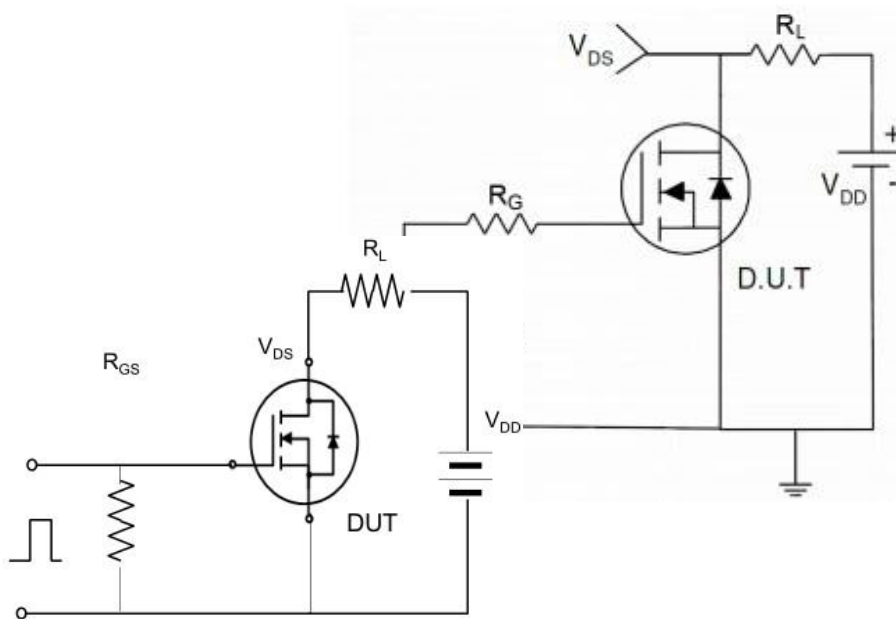
### 1) $E_{AS}$ Test Circuits



### 2) Gate Charge Test Circuit:

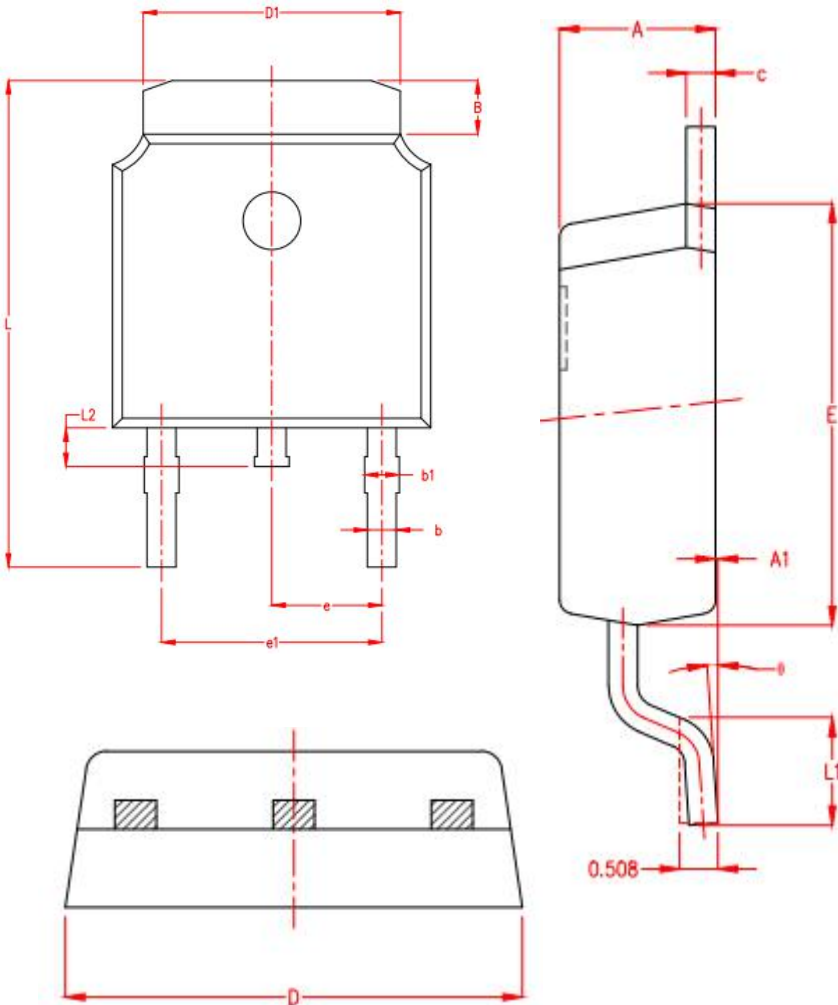


### 3) Switch Time Test Circuit:





### TO-252 Package Information



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	2.15	2.25	2.35
A1	0.00	0.06	0.12
B	0.96	1.11	1.26
b	0.59	0.69	0.79
b1	0.69	0.81	0.93
c	0.34	0.42	0.50
D	6.45	6.60	6.75
D1	5.23	5.33	5.43
E	5.95	6.10	6.25
e	2.286TYP.		
e1	4.47	4.57	4.67
L	9.90	10.10	10.30
L1	1.40	1.55	1.70
L2	0.60	0.80	1.00
$\theta$	0°	4°	8°